PCN Number:		2	20220824000.2					PCN Date:	Au	August 25, 2022	
Title: Adding CDAT-PR as additional wafer probe site											
Customer Contact:			PCN Manager Dept:					Quality Services			
Proposed 1 <sup>st</sup> Ship Date:		:	Feb 26, 2023			Estimate	stimated Sample Availability: Samples not supported				
Change Type	e:										
Assembly Site			Design						☐ Wafer Bump Site		
Assembly Process				Data Sheet					Wafer Bump Material		
Assembly Materials				Part number chang			nge		Wafer Bump Process		
Mechanical Specification			☐ Test Site					Wafer Fab Site			
Packing/Shipping/Labeline			g						Wafer Fab Materials		
□ Wafer Fab Process									rocess		
PCN Details											
Description of Change:											
Texas Instruments Incorporated has qualified CDAT-PR as an additional probe site for the devices listed											
below to support high volume ramps.											
Current: New:											
Probe Site			DL-MOS-4 (SCT)				TI Chengdu (CDAT-PR)				
Current Tester		,	VLCT	-			ETS364				
Test coverage	Test coverage, insertions, conditions will remain consistent with current testing.										
Reason for Change:											
Enable additional probe capacity to support high volume ramps.											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
None.											
Impact on Environmental Ratings											
None.											
Changes to product identification resulting from this PCN:											
None.											
<b>Product Affe</b>	ected:										
INA193AQD	BVRQ1	INA195	AQDBVF	RQ1	I	NA197AQDBV	QDBVRQ1				
INA194AQD	6AQDBVRQ1 INA198AQDBVR				'RQ1						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN www admin team@list.ti.com

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